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			ISSUE CLASSIFICATION

U.S. UTILITY Patent Application

QZ O.I.P.E. SCANNED <u>QW</u> Q.A. <u>AA</u>	PATENT DATE
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APPLICATION NO. 09/847667	CONT/PRIOR	CLASS 257	SUBCLASS 577	ART UNIT 2822 2827	EXAMINER Mitschell
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Method for bonding wafers to produce stacked integrated circuits

PTO-2040
12/89[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed. <input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____	_____ (Assistant Examiner) _____ (Date)			NOTICE OF ALLOWANCE MAILED	
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				Amount Due	Date Paid
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